



NC600 (Sn96/Ag4)
LEAD FREE
NO CLEAN DELTA®
SOLDER WIRE

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Description

Delta® Solder Wire NC600 is our no clean flux that promotes fast wetting action and maximum wetting spread. It is available in standard leaded alloys as well as high temperature lead-free alloys, such as Sn96/Ag4. NC600 contains a synthetic refined resin with a very effective activator so it performs like an RA type cored wire. NC600 exhibits virtually no spattering and conforms to J-STD-004B specifications.

Main Features

- ❑ Excellent wettability
- ❑ Hard non-conductive residues
- ❑ RoHs compliant

Technical Data (Flux Extract)

	Specification	Test Method
Color & Appearance	Light yellow opaque solid	Visual
Flux Classification	RELO	J-STD-004
Copper Mirror	No removal of copper film	IPC-TM-650 2.3.32
Corrosion	Pass	IPC-TM-650 2.6.15
SIR		
J-STD-004, Pattern Down	2.33 x 10 ¹¹	IPC-TM-650 2.6.3.3
Electromigration	Pass	Bellcore GR-78-CORE 13.1.4
Post Reflow Flux Residue	55%	TGA Analysis
Acid Value	190 - 210	IPC-TM-650 2.3.13
Flux Residue Dryness	Pass	IPC-TM-650 2.4.47
Spitting of Flux-Cored Solder	0.3%	IPC-TM-650 2.4.48
Solder Spread	100 mm ²	IPC-TM-650 2.4.46

Wire Diameter

Sn96/Ag4 alloy wire is available in a variety of diameters. The chosen diameter is based on application methods, pad size, and desired solder joint volume. Generally, the diameter of the wire should be slightly larger than the width/diameter of the joint or connection to be soldered. Below is a list of standard diameters.

Standard wire diameters

Diameter/Inch	0.125	0.092	0.062	0.050	0.040	0.032	0.028	0.025	0.020	0.015	0.010
Diameter/mm	3.18	2.33	1.57	1.27	1.01	0.81	0.71	0.63	0.51	0.38	0.25
Std.Wire Gauge	11	13	16	18	19	21	22	23	25	28	31
Tolerance, in.	+/-0.006	+/-0.005	+/-0.003	+/-0.003	+/-0.002	+/-0.002	+/-0.002	+/-0.002	+/-0.002	+/-0.002	+/-0.002

Flux Percentage

Qualitek utilizes a state-of-the-art automatic wire extrusion and wire drawing machines to manufacture consistent solder. The introduction of flux core in the wire extrusion process involves continual monitoring of flux percentage to ensure minimal flux voids and irregular wire. Typical flux percentage for lead free solder is **2.2-3.3%**.

Physical Properties

Solder Composition

Qualitek® Sn96/Ag4 is a eutectic lead-free alloy that conforms to and exceeds the impurity requirements of IPC-J-STD-006C and all other relevant international standards.

Typical Analysis													
Sn	Ag	Cu	Pb	Sb	Bi	In	As	Fe	Ni	Cd	Al	Zn	Au
Bal	3.5-4.5	0.080 Max	0.070 Max	0.200 Max	0.100 Max	0.100 Max	0.030 Max	0.020 Max	0.010 Max	0.002 Max	0.005 Max	0.003 Max	0.050 Max

	Sn96/Ag4	Sn63/Pb37
Melting Point, °C	221 E	183 E
Hardness, Brinell	15HB	14HB
Coefficient of Thermal Expansion	Pure Sn= 30.2	24.7
Tensile Strength, psi	3873	4442
Density, g/cc	7.5	8.42
Electrical Resistivity (μohm-cm)	12.3	14.5
Electrical Conductivity, %IACS	14.0	11.9

	Sn96/Ag4	Sn63/Pb37
Yield Strength, psi	3256	3950
Total Elongation,%	24	48
Joint Shear Strength, at 0.1mm/min 20 °C	27	23
Joint Shear Strength, at 0.1mm/min 100 °C	17	14
Creep Strength, N/mm ² at 0.1mm/min 20 °C	13.7	3.3
Creep Strength, N/mm ² at 0.1mm/min 100 °C	5	1
Thermal Conductivity, W/m.K	55.3	50.9

Flux Residues & Cleaning

NC600 is a no clean formulation; therefore, the residues do not need to be removed for typical applications. If residue removal is desired, the use of Everkleen 1005 Buffered Saponifier with a 5-15% concentration in hot 60 °C (140 °F) de-ionized water will aid in residue removal.

Storage & Shelf Life

Solder wire storage should be in a 65-80 °F environment away from direct heat. We recommend using gloves when handling solder wire directly. Solder wire has an indefinite shelf life.

Packaging

Qualitek flux-core wire and solid wire are packed in

12.5lb -box of ½ lb spools

25 lb -box of 1 lb spools

12.5kg -box of ½ kg spools

8 kg -box of 1kg spools

40 lb -box of 5 lb spools

20 lb -box of 20 lb spools

Disposal

Delta Solder Wire NC600 lead free solder should be disposed of in accordance with federal, state & local authority requirements.